SCAS122C – MARCH 1990 – REVISED SEPTEMBER 1996

25 2C

20E ||24

•	Members of the Texas Instruments <i>Widebus</i> ™ Family Inputs Are TTL-Voltage Compatible	SN54ACT16 74ACT163		DL P	ACKAGE
•	3-State Bus Driving True Outputs	, f	$\overline{\mathbf{U}}$	_	1
•		10E [· · ·] 1C
•	Full Parallel Access for Loading	1Q1 [- 6] 1D1
•	Flow-Through Architecture Optimizes	1Q2 [GND [] 1D2] GND
_	PCB Layout	1Q3		- 6] 1D3
•	Distributed V _{CC} and GND Pin Configuration	1Q4		- 6] 1D0] 1D4
-	Minimizes High-Speed Switching Noise	V _{CC}		- E] v _{cc}
•	EPIC [™] (Enhanced-Performance Implanted	1Q5] 1D5
	CMOS) 1-µm Process	1Q6 [9	40] 1D6
•	500-mA Typical Latch-Up Immunity at	GND [10	39] GND
	125°C	1Q7 🛛	11	38] 1D7
•	Package Options Include Shrink	1Q8 🛛		- 6] 1D8
	Small-Outline (DL) 300-mil Packages Using	2Q1 []		- F	2D1
	25-mil Center-to-Center Pin Spacings and	2Q2 []		- F	2D2
	380-mil Fine-Pitch Ceramic Flat (WD)	GND 🛛			GND
	Packages Using 25-mil Center-to-Center	2Q3 🏾		- E	2D3
	Pin Spacings	2Q4 🏾		- 6	2D4
doer	ription	V _{CC}		L	V _{CC}
uesi		2Q5 🛛		- 6	2D5
	The SN54ACT16373 and 74ACT16373 are 16-bit	2Q6 🛛			2D6
	D-type transparent latches with 3-state outputs			L	GND
	designed specifically for driving highly capacitive	2Q7 [- 6	2D7
	or relatively low-impedance loads. They are	2Q8	23	26	2D8

A buffered output-enable (\overline{OE}) input can be used to place the outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines in a bus-organized system without need for interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The 74ACT16373 is packaged in TI's shrink small-outline package, which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN54ACT16373 is characterized for operation over the full military temperature range of -55° C to 125° C. The 74ACT16373 is characterized for operation from -40° C to 85° C.



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particularly suitable for implementing buffer

registers, I/O ports, bidirectional bus drivers, and working registers. These devices can be used as two 8-bit latches or one 16-bit latch. The Q outputs of the latches follow the data (D) inputs if enable C is taken high. When C is taken low, the Q outputs are latched at the levels set up at the D inputs.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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SN54ACT16373, 74ACT16373 16-BIT D-TYPE TRANSPARENT LATCHES WITH 3-STATE OUTPUTS SCAS122C - MARCH 1990 - REVISED SEPTEMBER 1996

	FUNCTION TABLE											
	INPUTS	OUTPUT										
ŌE	С	Q										
L	Н	Н	Н									
L	н	L	L									
L	L	Х	Q ₀									
Н	Х	Х	Z									

logic symbol[†]

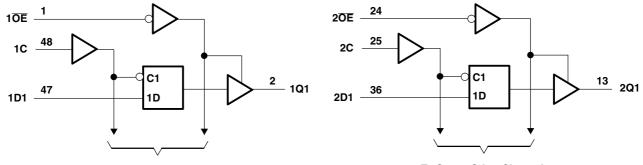
10E	1	1EN				
1C	48	C1				
2 <u>0E</u>	24	2EN				
20L 2C	25	C4				
20		Ľ				
1D1	47	1D	1	2 ▽	2	1Q1
1D2	46		•		3	1Q2
1D3	44	<u> </u>			5	1Q3
1D4	43	<u> </u>			6	1Q4
1D5	41	<u> </u>			8	1Q5
1D6	40	<u> </u>			9	1Q6
1D7	38	<u> </u>			11	1Q7
1D8	37				12	1Q8
2D1	36	3D	1	4 ▽	13	2Q1
2D1	35	00		4 *	14	2Q2
2D3	33				16	2Q3
2D3	32				17	2Q4
2D4	30				19	2Q5
2D5	29	<u> </u>			20	2Q6
2D0	27				22	2Q7
2D7	26	<u> </u>			23	2Q8
200						230

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



SCAS122C - MARCH 1990 - REVISED SEPTEMBER 1996

logic diagram (positive logic)



To Seven Other Channels

To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to V _{CC} + 0.5 V
Output voltage range, V _O (see Note 1)	–0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): DL package	1.2 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

		SN54AC	T16373	74ACT	16373	
		MIN	МАХ	MIN	MAX	UNIT
V _{CC}	Supply voltage (see Note 4)	4.5	5.5	4.5	5.5	V
V _{IH}	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0	V _{CC}	0	V_{CC}	V
Vo	Output voltage	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current		-24		-24	mA
I _{OL}	Low-level output current		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	0	10	ns/V
T _A	Operating free-air temperature	-55	125	-40	85	°C

NOTES: 3. Unused inputs should be tied to V_{CC} through a pullup resistor of approximately 5 k Ω or greater to prevent them from floating. 4. All V_{CC} and GND pins must be connected to the proper voltage supply.



SCAS122C - MARCH 1990 - REVISED SEPTEMBER 1996

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			T,	_A = 25°C		SN54AC	T16373	74AC1	16373	
PARAMETER	TEST CONDITIONS	v _{cc}	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		4.5 V	4.4			4.4		4.4		
	I _{OH} = –50 μA	5.5 V	5.4			5.4		5.4		
	1 04 mA	4.5 V	3.94			3.7		3.8		
V _{OH}	I _{OH} = -24 mA	5.5 V	4.94			4.7		4.8		V
	$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V				3.85				
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V						3.85		
		4.5 V			0.1		0.1		0.1	
	I _{OL} = 50 μA	5.5 V			0.1		0.1		0.1	v
	1 04 mA	4.5 V			0.36		0.5		0.44	
V _{OL}	I _{OL} = 24 mA	5.5 V			0.36		0.5		0.44	
	$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V					1.65			
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V							1.65	
lı	V _I = V _{CC} or GND	5.5 V			±0.1		±1		±1	μA
I _{OZ}	$V_{O} = V_{CC}$ or GND	5.5 V			±0.5		±10		±5	μA
I _{CC}	$V_{I} = V_{CC}$ or GND, $I_{O} = 0$	5.5 V			8		160		80	μA
ΔI_{CC}^{\ddagger}	One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V			0.9		1		1	mA
Ci	$V_I = V_{CC}$ or GND	5 V		4.5						pF
Co	$V_I = V_{CC}$ or GND	5 V		12						pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V to V_{CC}.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		T _A = 2	25°C	SN54AC	T16373	74AC1	16373	
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _w	Pulse duration, LE high	4		4		1		ns
t _{su}	Setup time, data before LE \downarrow	1		1		1		ns
t _h	Hold time, data after LE \downarrow	5		5		5		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

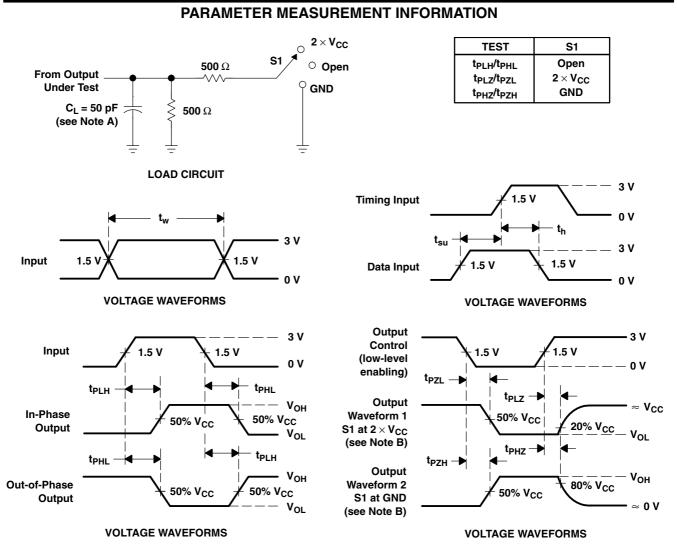
PARAMETER	FROM	то	T,	ק = 25°C	;	SN54AC	T16373	74ACT16373		UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	ТҮР	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}	D	0	3.8	7.9	9.4	3.8	11.8	3.8	11.1	
t _{PHL}	D	Q	3.1	8.2	9.7	3.1	13	3.1	12.3	ns
t _{PLH}		<u> </u>	4.6	9.3	10.8	4.6	13.7	4.6	12.8	-
t _{PHL}	LE	Q	4.5	9.1	10.5	4.5	13	4.5	12.2	ns
t _{PZH}		0	3.1	8	9.5	3.1	13	3.1	12.1	
t _{PZL}	ŌĒ	Q	3.8	9.4	11.1	3.8	15.1	3.8	14.2	ns
t _{PHZ}	05	0	5.3	8.6	9.9	5.3	11	5.3	5.3 10.7	
t _{PLZ}	ŌĒ	Q	4.3	7.4	8.7	4.3	9.8	4.3	9.4	ns



SCAS122C - MARCH 1990 - REVISED SEPTEMBER 1996

operating characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

		PARAMETER	TEST CO	TYP	UNIT		
	Deven dissignation over sites and such that	Outputs enabled	0 50		43		
	C _{pd}	Power dissipation capacitance per latch	Outputs disabled	C _L = 50 pF,	f = 1 MHz	4.5	pF



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z₀ = 50 Ω , t_r = 3 ns, t_f = 3 ns.
 - D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9202401MXA	ACTIVE	CFP	WD	48	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9202401MX A SNJ54ACT16373W D	Samples
74ACT16373DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16373	Samples
74ACT16373DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16373	Samples
74ACT16373DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16373	Samples
SNJ54ACT16373WD	ACTIVE	CFP	WD	48	1	TBD	Call TI	N / A for Pkg Type		5962-9202401MX A SNJ54ACT16373W D	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



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⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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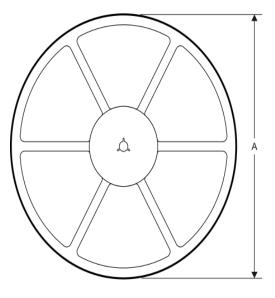
PACKAGE MATERIALS INFORMATION

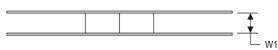
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TAPE AND REEL INFORMATION

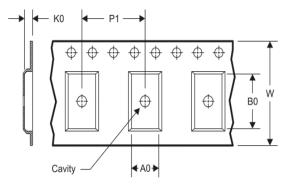
REEL DIMENSIONS

Texas Instruments





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT16373DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

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PACKAGE MATERIALS INFORMATION

14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ACT16373DLR	SSOP	DL	48	1000	367.0	367.0	55.0

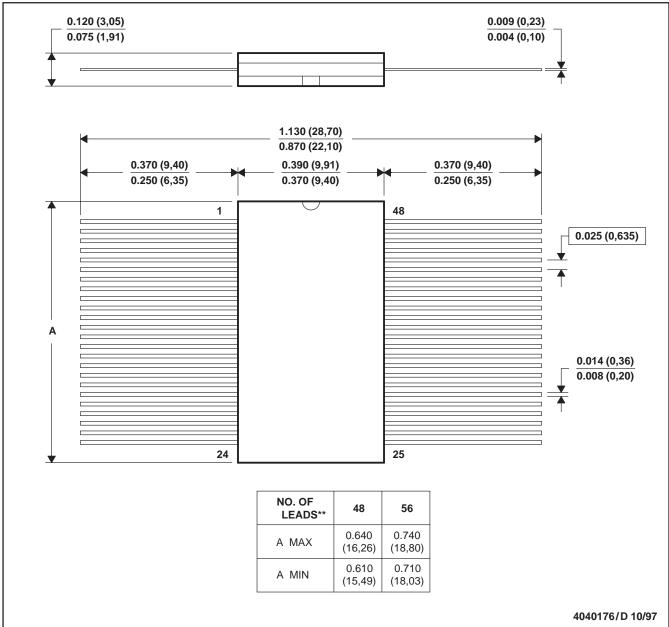
MECHANICAL DATA

MCFP010B - JANUARY 1995 - REVISED NOVEMBER 1997

CERAMIC DUAL FLATPACK

WD (R-GDFP-F**)

48 LEADS SHOWN

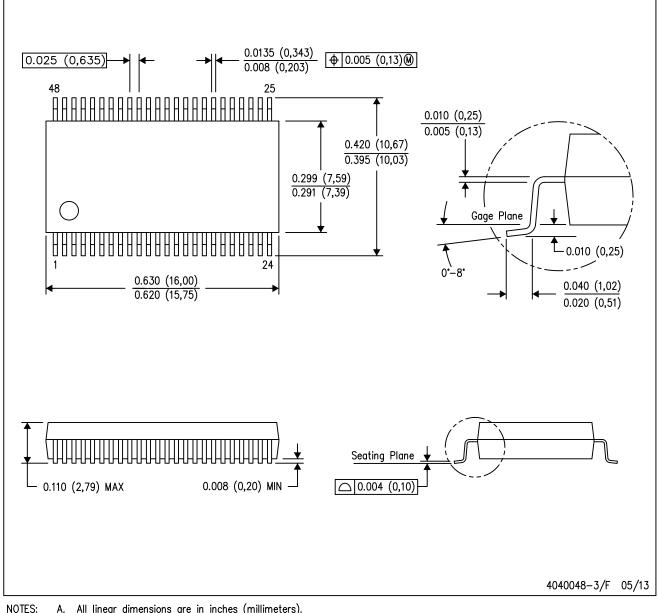


- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only
 - E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA
 - GDFP1-F56 and JEDEC MO-146AB



DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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